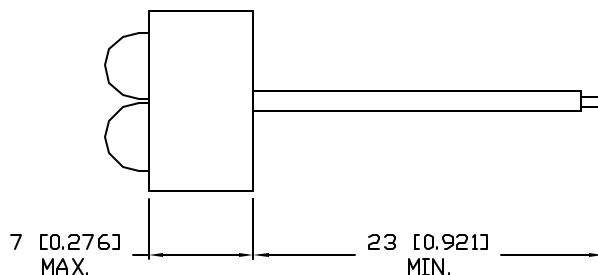
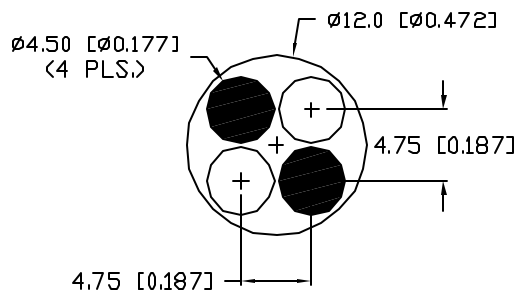


UNCONTROLLED DOCUMENT

PART NUMBER
SSP-LXC04762S4A

REV.
A

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR.	10.16.03



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20/40\text{mA}$

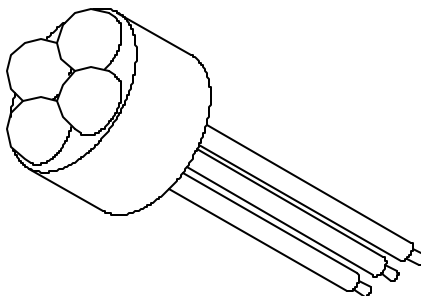
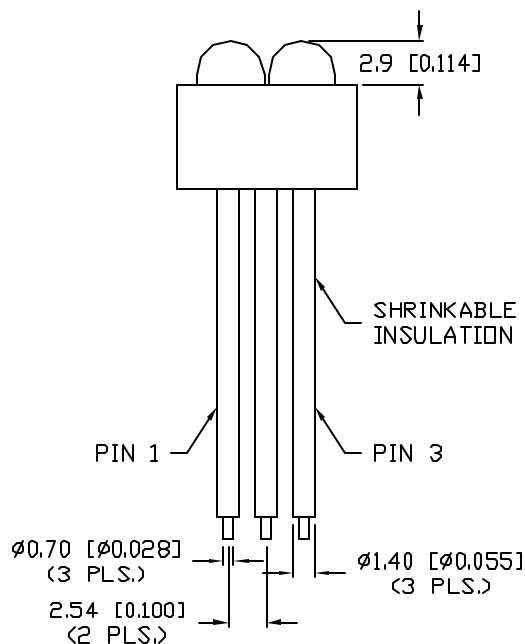
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660 (R)		nm	
		565 (G)		nm	
FORWARD VOLTAGE* (R/G)		3.6/4.4	4.6/5.2	V _f	
REVERSE VOLTAGE (R/G)	4.0/5.0			V _r	$I_f=100\mu\text{A}$
AXIAL INTENSITY** (R/G)		2000/300		mcd	$I_f=20/40\text{mA}$
VIEWING ANGLE		30		2x theta	
EMITTED COLOR:	RED/GREEN				
EPOXY LENS FINISH:	WATER CLEAR				

* VOLTAGE FOR PIN 1/VOLTAGE FOR PIN 3
** INTENSITY PER DIE. TEST CONDITION: CURRENT FOR PIN 1/PIN 3

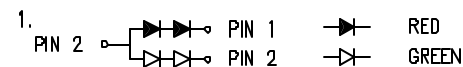
LIMITS OF SAFE OPERATION AT 25°C PER DIE

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		150	mA
STEADY CURRENT	(R/G)	30/25	mA
POWER DISSIPATION		105	mW
DERATE FROM 25°C		-1.2	mW/°C
OPERATING, STORAGE TEMP.		-30 TO +70	°C
SOLDERING TEMP.		+260	°C
2.0mm FROM BODY			3 SEC. MAX

* $t < 10\mu\text{s}$



NOTES: PIN OUT



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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.038), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= ^{+DECIMAL PRECISION} -0.00 MAX= ^{+0.00} -DECIMAL PRECISION

REV. A PART NUMBER SSP-LXC04762S4A

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0.47" CIRCULAR, 4 LED CLUSTER, DUAL COLOR,
660nm SUPER RED LEDS, 565nm SUPER GREEN LEDS,
WATER CLEAR LENS, COMMON ANODE.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN: BC CHECKED: APPROVED: DATE: 1.14.00
PAGE: 1 OF 1